

### General Description



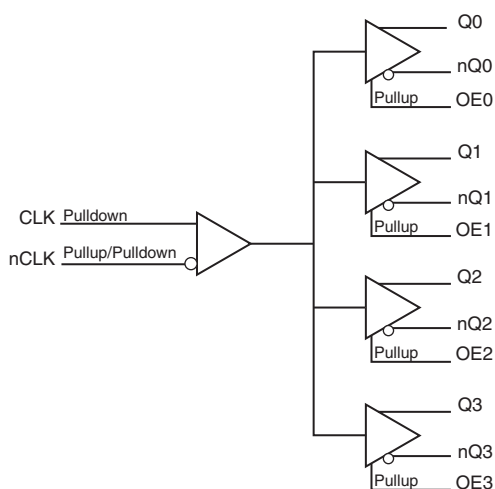
The ICS854104 is a low skew, high performance 1-to-4 Differential-to-LVDS Clock Fanout Buffer and a member of the HiPerClockS™ family of High Performance Clock Solutions from IDT. Utilizing Low Voltage Differential Signaling (LVDS), the ICS854104 provides a low power, low noise, solution for distributing clock signals over controlled impedances of 100Ω. The ICS854104 accepts a differential input level and translates it to LVDS output levels.

Guaranteed output and part-to-part skew characteristics make the ICS854104 ideal for those applications demanding well defined performance and repeatability.

### Features

- Four differential LVDS output pairs
- One differential clock input pair
- CLK/nCLK can accept the following differential input levels: LVPECL, LVDS, LVHSTL, HCSL, SSTL
- Each output has an individual OE control
- Maximum output frequency: 700MHz
- Translates differential input signals to LVDS levels
- Additive phase jitter, RMS: 0.232ps (typical)
- Output skew: 50ps (maximum)
- Part-to-part skew: 350ps (maximum)
- Propagation delay: 1.3ns (maximum)
- 3.3V operating supply
- 0°C to 70°C ambient operating temperature
- Available in both standard (RoHS 5) and lead-free (RoHS 6) packages

### Block Diagram



### Pin Assignment

OE0	1	16	Q0
OE1	2	15	nQ0
OE2	3	14	Q1
V <sub>DD</sub>	4	13	nQ1
GND	5	12	Q2
CLK	6	11	nQ2
nCLK	7	10	Q3
OE3	8	9	nQ3

**ICS854104**

**16-Lead TSSOP**

**4.4mm x 5.0mm x 0.925mm package body**

**G Package**

**Top View**

**Table 1. Pin Descriptions**

Number	Name	Type		Description
1	OE0	Input	Pullup	Output enable pin for Q0, nQ0 outputs. See Table 3. LVCMOS/LVTTL interface levels.
2	OE1	Input	Pullup	Output enable pin for Q1, nQ1 outputs. See Table 3. LVCMOS/LVTTL interface levels.
3	OE2	Input	Pullup	Output enable pin for Q2, nQ2 outputs. See Table 3. LVCMOS/LVTTL interface levels.
4	V <sub>DD</sub>	Power		Positive supply pin.
5	GND	Power		Power supply ground.
6	CLK	Input	Pulldown	Non-inverting differential clock input.
7	nCLK	Input	Pullup/Pulldown	Inverting differential clock input. V <sub>DD</sub> /2 default when left floating.
8	OE3	Input	Pullup	Output enable pin for Q3, nQ3 outputs. See Table 3. LVCMOS/LVTTL interface levels.
9, 10	nQ3, Q3	Output		Differential output pair. LVDS interface levels.
11, 12	nQ2, Q2	Output		Differential output pair. LVDS interface levels.
13, 14	nQ1, Q1	Output		Differential output pair. LVDS interface levels.
15, 16	nQ0, Q0	Output		Differential output pair. LVDS interface levels.

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, *Pin Characteristics*, for typical values.

**Table 2. Pin Characteristics**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
R <sub>PULLUP</sub>	Input Pullup Resistor			51		kΩ
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		kΩ

## Function Table

**Table 3. Output Enable Function Table**

Inputs	Outputs
OE[3:0]	Q[0:3], nQ[0:3]
0	High-Impedance
1	Active (default)

## Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Supply Voltage, $V_{DD}$	4.6V
Inputs, $V_I$	-0.5V to $V_{DD} + 0.5V$
Outputs, $I_O$ (LVDS) Continuous Current Surge Current	10mA 15mA
Package Thermal Impedance, $\theta_{JA}$	100.3°C/W (0 mps)
Storage Temperature, $T_{STG}$	-65°C to 150°C

## DC Electrical Characteristics

**Table 4A. LVDS Power Supply DC Characteristics,  $V_{DD} = 3.3V \pm 5\%$ ,  $T_A = 0^\circ C$  to  $70^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Positive Supply Voltage		3.135	3.3	3.465	V
$I_{DD}$	Power Supply Current				75	mA

**Table 4B. LVCMOS/LVTTL DC Characteristics,  $V_{DD} = 3.3V \pm 5\%$ ,  $T_A = 0^\circ C$  to  $70^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{IH}$	Input High Voltage		2		$V_{DD} + 0.3$	V
$V_{IL}$	Input Low Voltage		-0.3		0.8	V
$I_{IH}$	Input High Current	$V_{DD} = V_{IN} = 3.465V$			150	$\mu A$
$I_{IL}$	Input Low Current	$V_{DD} = 3.465V, V_{IN} = 0V$	-5			$\mu A$

**Table 4C. Differential DC Characteristics,  $V_{DD} = 3.3V \pm 5\%$ ,  $T_A = 0^\circ C$  to  $70^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$I_{IH}$	Input High Current	CLK, nCLK $V_{DD} = V_{IN} = 3.465V$			150	$\mu A$
$I_{IL}$	Input Low Current	CLK $V_{DD} = 3.465V, V_{IN} = 0V$	-5			$\mu A$
		nCLK $V_{DD} = 3.465V, V_{IN} = 0V$	-150			$\mu A$
$V_{PP}$	Peak-to-Peak Voltage; NOTE 1		0.15		1.3	V
$V_{CMR}$	Common Mode Input Voltage; NOTE 1, 2		GND + 0.5		$V_{DD} - 0.85$	V

NOTE 1:  $V_{IL}$  should not be less than -0.3V.

NOTE 2: Common mode input voltage is defined as  $V_{IH}$ .

**Table 4D. LVDS DC Characteristics,  $V_{DD} = 3.3V \pm 5\%$ ,  $T_A = 0^\circ C$  to  $70^\circ C$** 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{OD}$	Differential Output Voltage		250	350	450	mV
$\Delta V_{OD}$	$V_{OD}$ Magnitude Change				50	mV
$V_{OS}$	Offset Voltage		1.2	1.3	1.45	V
$\Delta V_{OS}$	$V_{OS}$ Magnitude Change				50	mV

**Table 5. AC Characteristics,  $V_{DD} = 3.3V \pm 5\%$ ,  $T_A = 0^\circ C$  to  $70^\circ C$** 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$f_{MAX}$	Output Frequency				700	MHz
$t_{PD}$	Propagation Delay; NOTE 1		0.9		1.3	ns
$\tau_{jit}$	Buffer Additive Phase Jitter, RMS; refer to Additive Phase Jitter Section	155.52MHz, Integration Range: 12kHz – 20MHz)		0.232		ps
$tsk(o)$	Output Skew; NOTE 2, 4				50	ps
$tsk(pp)$	Part-to-Part Skew; NOTE 3, 4				350	ps
$t_R / t_F$	Output Rise/Fall Time	20% to 80%	180		660	ps
odc	Output Duty Cycle		45		55	%

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE: All parameters measured at  $f_{MAX}$  unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at the differential crossing point of the input to the differential output crossing point.

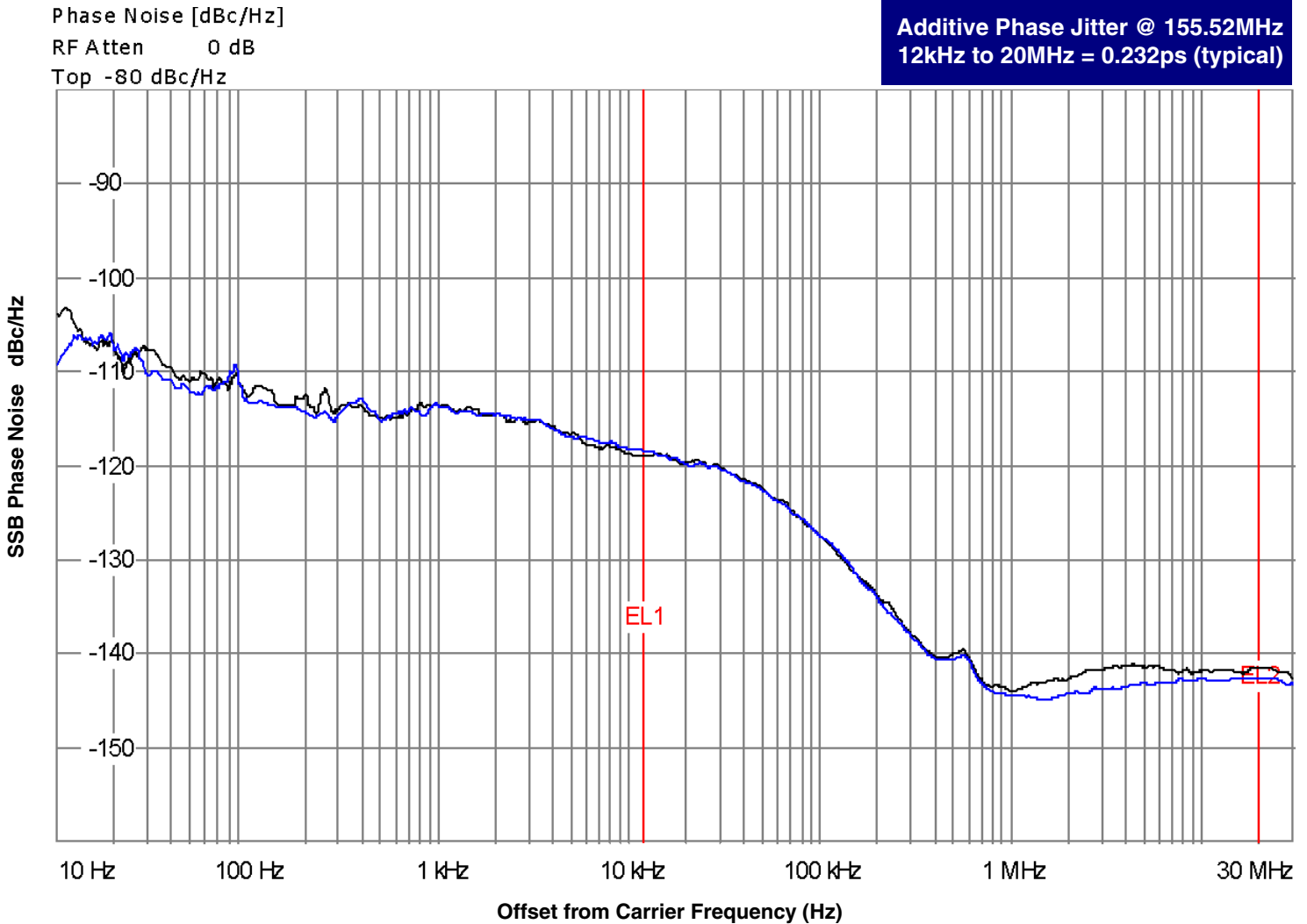
NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

## Additive Phase Jitter

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the ***dBc Phase Noise***. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a ratio

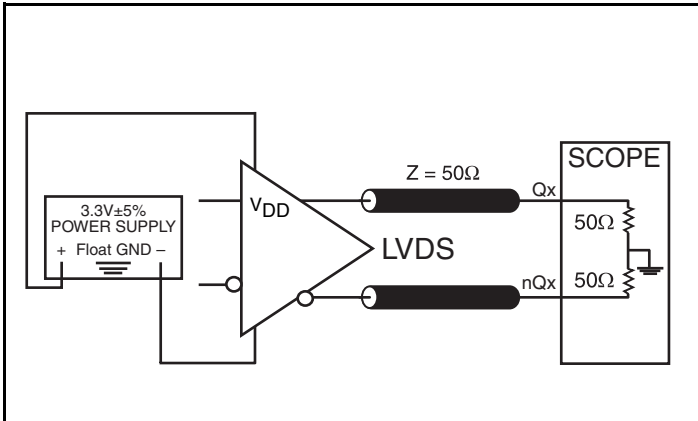
of the power in the 1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a ***dBc*** value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.



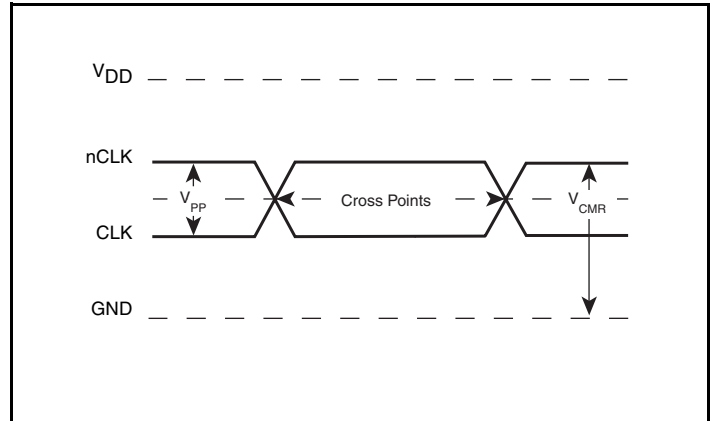
As with most timing specifications, phase noise measurements has issues relating to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the device. This

is illustrated above. The device meets the noise floor of what is shown, but can actually be lower. The phase noise is dependent on the input source and measurement equipment.

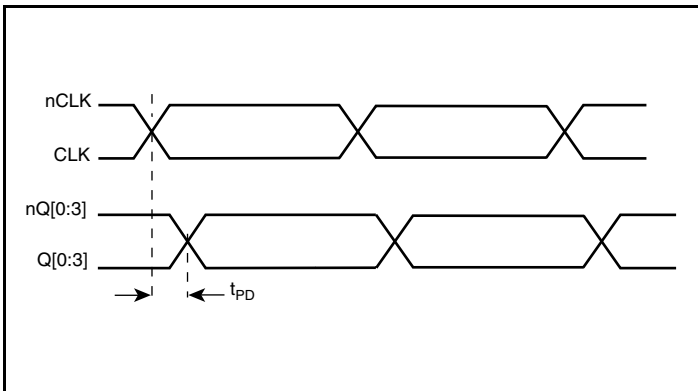
### Parameter Measurement Information



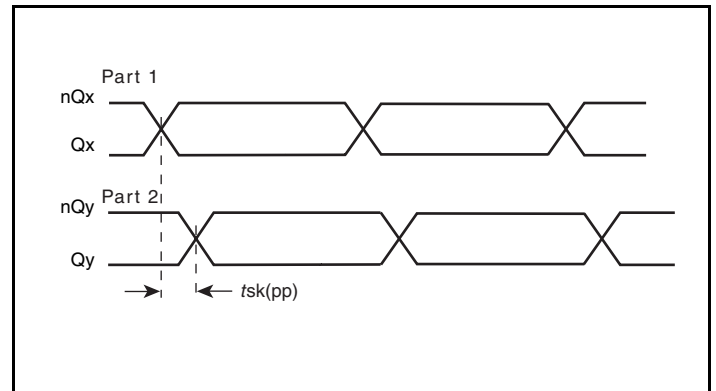
3.3V LVDS Output Load AC Test Circuit



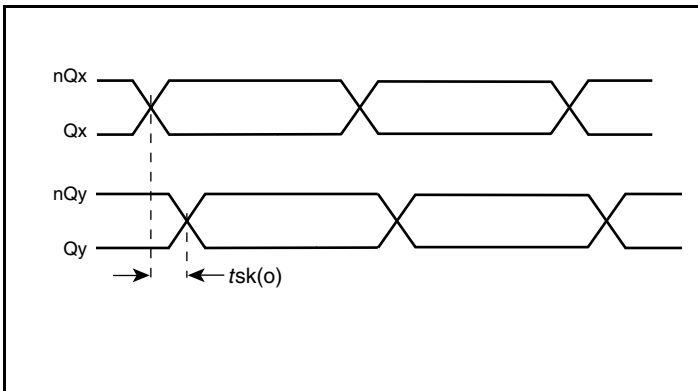
Differential Input Level



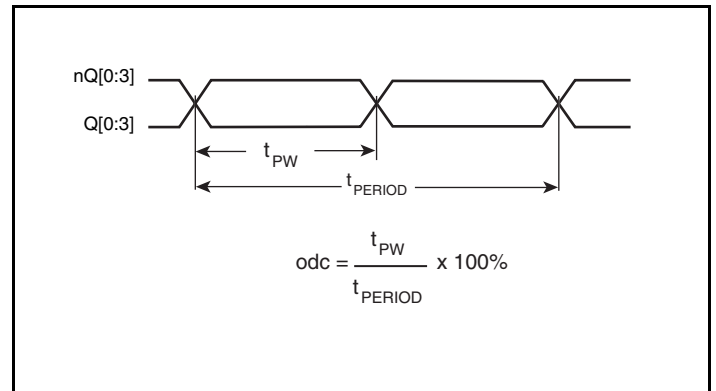
Propagation Delay



Part-to-Part Skew

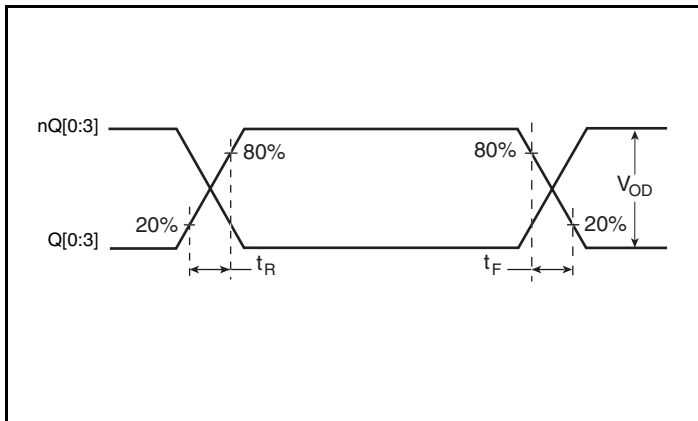


Output Skew

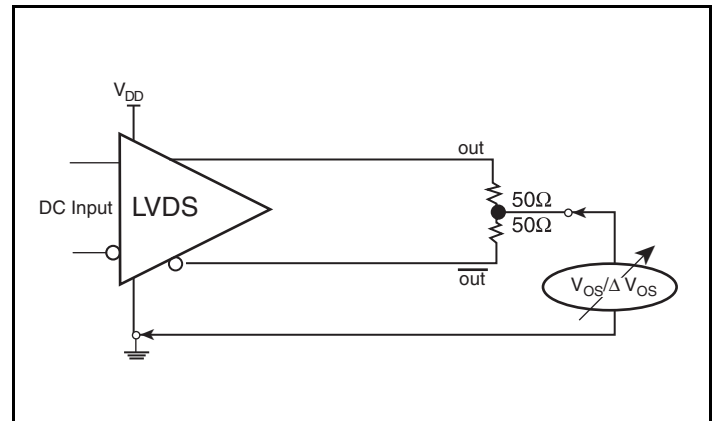


Output Duty Cycle/Pulse Width/Period

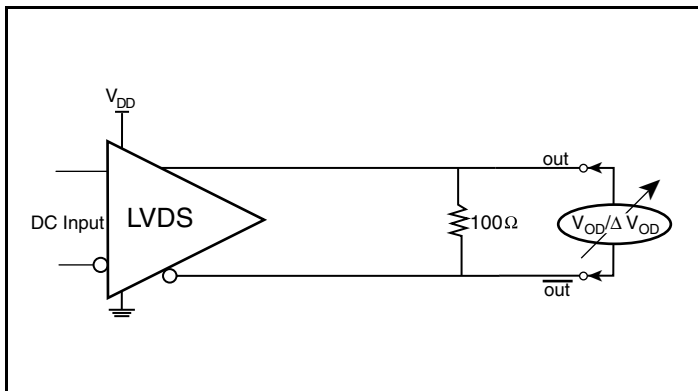
## Parameter Measurement Information, continued



Output Rise/Fall Time



Offset Voltage Setup



Differential Output Voltage Setup

## Application Information

### Wiring the Differential Input to Accept Single-Ended Levels

Figure 1 shows how the differential input can be wired to accept single-ended levels. The reference voltage  $V_{REF} = V_{DD}/2$  is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio of R1 and R2 might need to be adjusted to position the  $V_{REF}$  in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and  $V_{DD} = 3.3V$ ,  $V_{REF}$  should be 1.25V and  $R2/R1 = 0.609$ .

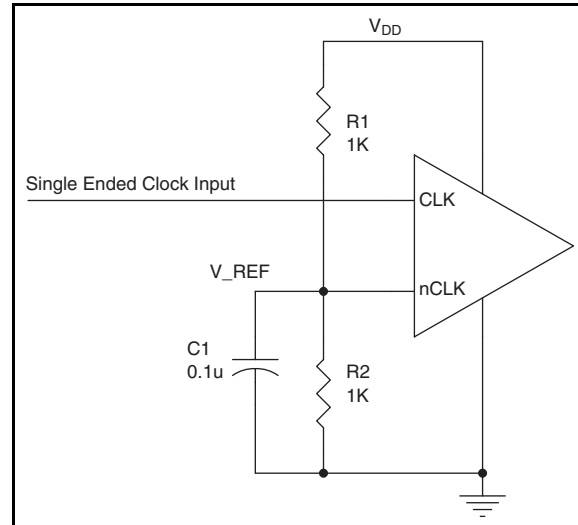


Figure 1. Single-Ended Signal Driving Differential Input

### Recommendations for Unused Input and Output Pins

#### Inputs:

##### LVC MOS Control Pins

All control pins have internal pullups; additional resistance is not required but can be added for additional protection. A 1k $\Omega$  resistor can be used.

#### Outputs:

##### LVDS Outputs

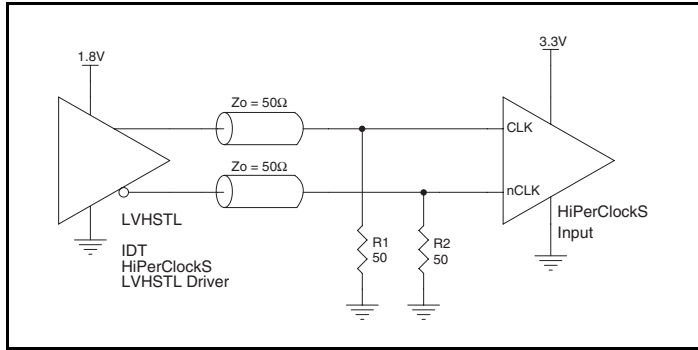
All unused LVDS output pairs can be either left floating or terminated with 100 $\Omega$  across. If they are left floating, there should be no trace attached.



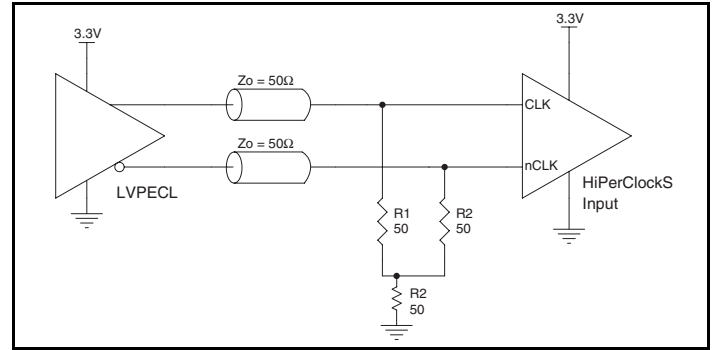
### Differential Clock Input Interface

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both signals must meet the  $V_{PP}$  and  $V_{CMR}$  input requirements. Figures 2A to 2F show interface examples for the HiPerClockS CLK/nCLK input driven by the most common driver types. The input interfaces suggested here are examples only.

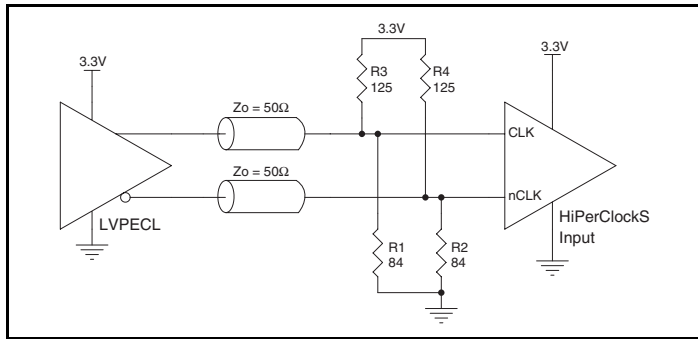
Please consult with the vendor of the driver component to confirm the driver termination requirements. For example, in Figure 2A, the input termination applies for IDT HiPerClockS open emitter LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.



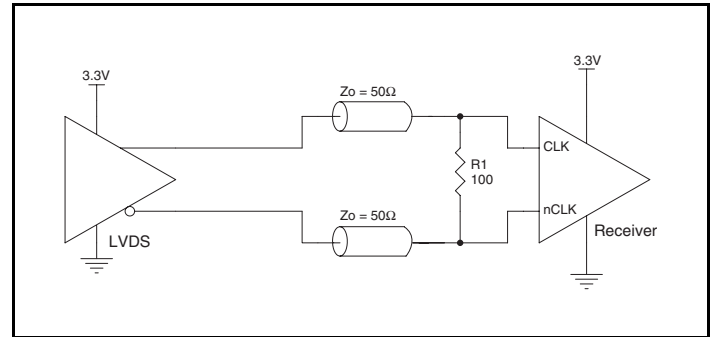
**2A. HiPerClockS CLK/nCLK Input Driven by an IDT Open Emitter HiPerClockS LVHSTL Driver**



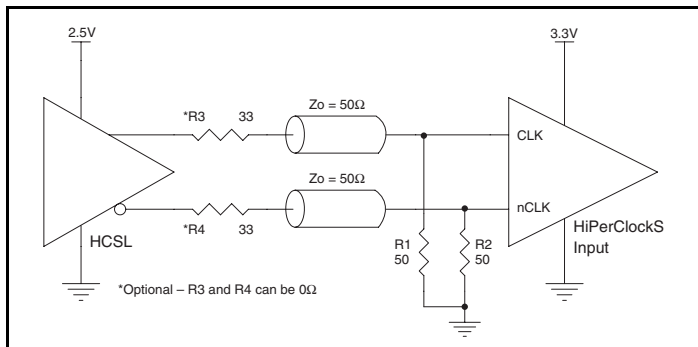
**Figure 2B. HiPerClockS CLK/nCLK Input Driven by a 3.3V LVPECL Driver**



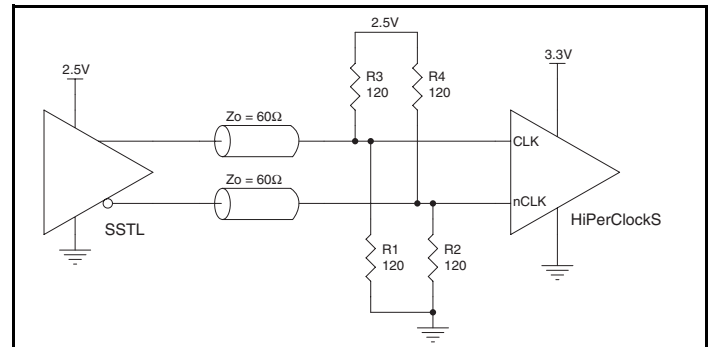
**Figure 3C. HiPerClockS CLK/nCLK Input Driven by a 3.3V LVPECL Driver**



**Figure 2D. HiPerClockS CLK/nCLK Input Driven by a 3.3V LVDS Driver**



**Figure 2E. HiPerClockS CLK/nCLK Input Driven by a 3.3V HCSL Driver**

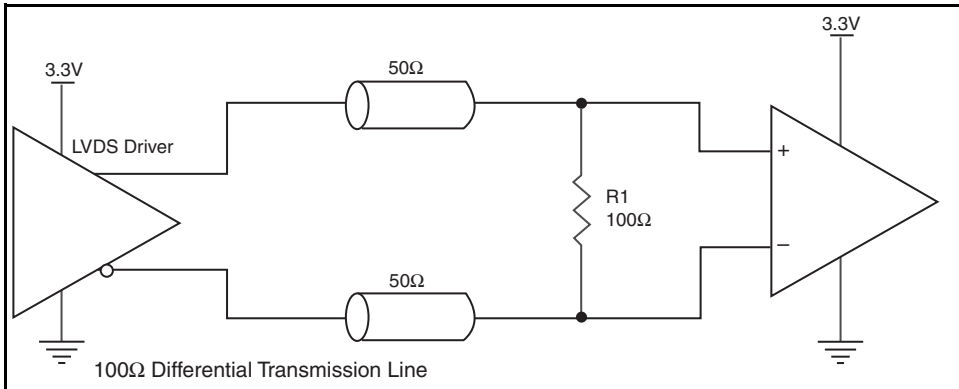


**Figure 2F. HiPerClockS CLK/nCLK Input Driven by a 2.5V SSTL Driver**

### 3.3V LVDS Driver Termination

A general LVDS interface is shown in *Figure 3*. In a  $100\Omega$  differential transmission line environment, LVDS drivers require a matched load termination of  $100\Omega$  across near the receiver input.

For a multiple LVDS outputs buffer, if only partial outputs are used, it is recommended to terminate the unused outputs.



**Figure 3. Typical LVDS Driver Termination**

## Power Considerations

This section provides information on power dissipation and junction temperature for the ICS854104. Equations and example calculations are also provided.

### 1. Power Dissipation.

The total power dissipation for the ICS854104 is the sum of the core power plus the analog power plus the power dissipated in the load(s). The following is the power dissipation for  $V_{DD} = 3.3V + 5\% = 3.465V$ , which gives worst case results.

- $\text{Power (core)}_{MAX} = V_{DD\_MAX} * I_{DD\_MAX} = 3.465V * 75mA = \mathbf{259.875mW}$

### 2. Junction Temperature.

Junction temperature,  $T_j$ , is the temperature at the junction of the bond wire and bond pad directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS devices is 125°C. Limiting the internal transistor junction temperature,  $T_j$ , to 125°C ensures that the bond wire and bond pad temperature remains below 125°C.

The equation for  $T_j$  is as follows:  $T_j = \theta_{JA} * Pd\_total + T_A$

$T_j$  = Junction Temperature

$\theta_{JA}$  = Junction-to-Ambient Thermal Resistance

$Pd\_total$  = Total Device Power Dissipation (example calculation is in section 1 above)

$T_A$  = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance  $\theta_{JA}$  must be used. Assuming no air flow and a multi-layer board, the appropriate value is 100.3°C/W per Table 6 below.

Therefore,  $T_j$  for an ambient temperature of 70°C with all outputs switching is:

$$70^\circ\text{C} + 0.260\text{W} * 100.3^\circ\text{C/W} = 96.1^\circ\text{C}. \text{ This is well below the limit of } 125^\circ\text{C}.$$

This calculation is only an example.  $T_j$  will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (multi-layer).

**Table 6. Thermal Resistance  $\theta_{JA}$  for 16 Lead TSSOP, Forced Convection**

$\theta_{JA}$ by Velocity			
Meters per Second	0	1	2.5
Multi-Layer PCB, JEDEC Standard Test Boards	100.3°C/W	96.0°C/W	93.9°C/W

## Reliability Information

Table 7.  $\theta_{JA}$  vs. Air Flow Table for a 16 Lead TSSOP

$\theta_{JA}$ by Velocity			
Meters per Second	0	1	2.5
Multi-Layer PCB, JEDEC Standard Test Boards	100.3°C/W	96.0°C/W	93.9°C/W

## Transistor Count

The transistor count for ICS854104 is: 286

Pin compatible with SN65LVDS104

## Package Outline and Package Dimensions

Package Outline - G Suffix for 16 Lead TSSOP

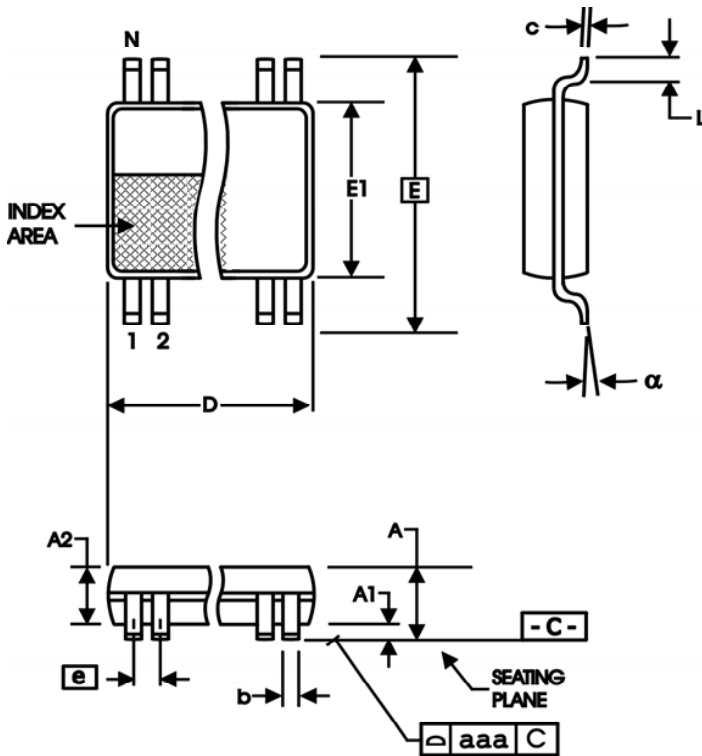


Table 8. Package Dimensions

All Dimensions in Millimeters		
Symbol	Minimum	Maximum
N	16	
A		1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	4.90	5.10
E	6.40 Basic	
E1	4.30	4.50
e	0.65 Basic	
L	0.45	0.75
$\alpha$	0°	8°
aaa	0.10	

Reference Document: JEDEC Publication 95, MO-153

## Ordering Information

Table 9. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
854104AG	854104AG	16 Lead TSSOP	Tube	0°C to 70°C
854104AGT	854104AG	16 Lead TSSOP	2500 Tape & Reel	0°C to 70°C
854104AGLF	854104AL	"Lead-Free" 16 Lead TSSOP	Tube	0°C to 70°C
854104AGLFT	854104AL	"Lead-Free" 16 Lead TSSOP	2500 Tape & Reel	0°C to 70°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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## Revision History Sheet

Rev	Table	Page	Description of Change	Date
A	T5	4	AC Characteristics - deleted "Bank A" test conditions from part-to-part skew row.	8/13/09



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